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Linliu

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[54] **PLANARIZATION PROCESS USING ARTIFICIAL GRAVITY**

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Related U.S. Application Data

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[51] **Int. Cl.⁶** **B05C 11/02**

[52] **U.S. Cl.** **118/52; 118/636**

[58] **Field of Search** 427/240; 118/52, 118/54, 636

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[57] **ABSTRACT**

The time needed to planarize the surface of an integrated circuit is reduced by causing the planarization liquid to settle in the presence of artificial gravity that supplements natural gravity. A number of different ways to achieve artificial gravity are described. These include centrifuging, magnetic repulsion, vertical pulling by a motor, and providing a pressure differential between the top and bottom sides of the wafer holder.

9 Claims, 4 Drawing Sheets

